From	To	Room/Event	Type
Time		Day 1: Monday - October 27, 2025	
3:00 PM	5:00 PM	Registration Opens - Grand Foyer, Main Level	ASME Meetings
6:30 PM	8:30 PM	Leadership Dinner -By invitation Only	

Time		Day 2: Tuesday - October 28, 2025				
From	To	Room/Event				Type
8:00 AM	8:30 AM	Room: California Ballroom, Main Floor				ASME Meetings
		InterPACK'25 -Opening Remarks by General Chair				
8:30 AM	9:30 AM	Room: California Ballroom, Main Level				Plenary Session
		Materials Engineering Innovations for Advanced Electronics Cooling By Prof. Ken Goodson				
9:30 AM	11:00 AM	Room: Lassen, 2nd Floor	Room: Tahoe, 2nd Floor	Room: Yosemite, 2nd Floor	Room: Sierra, 2nd Floor	Technical Sessions
		01-01: Heterogeneous Integration - I	02-01: Single Phase Liquid Cooling - I	03-01: Electronics Packaging - Assembly and Encapsulation	11-01:Advanced Simulation in Science and Engineering - I	
11:00 AM	11:15 AM	Room: Grand Foyer, Main Floor				Break
		Coffee Break				
11:15 AM	12:45 PM	Room: Lassen, 2nd Floor	Room: Sequoia, 2nd Floor	Room: Yosemite, 2nd Floor	Room: The Palm, Main Floor	Technical Sessions
		09-01:Micro/Nano Mechatronics, Microelectronics, Microelectrochemical Systems, and their Applications of Internet of Things - I	02-02: Two Phase Cooling - I	03-02: Electronics Packaging - Power Electronics and Batteries	Thermal/Mechanical/Electrical Challenges and Opportunities for Mobile/Wireless/AI/IoT/Automotive and Higher Power Compute Devices	Panel
12:45 PM	2:00 PM	Room: Hermosa/Huntington/Manhattan, Main Floor				Lunch Presentation
		LunchAvram Bar-Cohen Award				
2:00 PM	3:30 PM	Room: Laguna, Main Floor		Room: Newport, Main Floor		Tutorials
		Efficient Thermo-Mechanical Simulations Using Compact Models		Center for Energy-Smart Electronic Systems (ES2)		Workshops
3:30 PM	3:45 PM	Room: Grand Foyer, Main Floor				Break
		Coffee Break				
3:45 PM	5:15 PM	Room: Lassen, 2nd Floor	Room: Tahoe/Redwood, 2nd Floor	Room: Sequoia, 2nd Floor	Room: Sierra, 2nd Floor	Technical Sessions
		06-01: Process Monitoring & Modeling for Additive Electronics	04-01: Power/RF Electronics and Photonics - Emerging Active Cooling & Reliability	03-03: Electronics Packaging - Solders I	Session 05-03: Multiscale Thermal Transport and Energy Storage - III	
5:15 PM	5:45 PM	Room: Lassen, 2nd Floor				ASME Meetings
		MIPE Meeting				
5:45 PM	7:00 PM	Room: Grand Ballroom, Main Floor				Student Posters
		Interactive Poster Presentations				
7:00 PM	7:45 PM	Room: International Center				ASME Meetings
		EPPD + JEP Meeting (Open)				

Time		Day 3: Wednesday - October 29, 2025				
From	To	Room/Event				Type
8:00 AM	9:30 AM	Room: California Ballroom, Main Level				Plenary Session
		Special Panel on Electronics Packaging and Smart Manufacturing for AI Applications				
		Room: Lassen, 2nd Floor	Room: Sequoia, 2nd Floor	Room: Yosemite, 2nd Floor	Room: Newport, Main Floor	Technical Sessions

9:30 AM	11:00 AM	06-02: Printed Electronics for Defense & Extreme Environments	02-03: Data Center Metrics and Modeling	03-04: Electronics Packaging - Thermal Management	AI, Investment and Industry Trends	Tutorials
11:00 AM	11:15 AM	Room: Grand Foyer, Main Floor				Break
		Coffee Break				
11:15 AM	12:45 PM	Room: Lassen, 2nd Floor	Room: Tahoe/Redwood, 2nd Floor	Room: Yosemite, 2nd Floor	Room: Laguna, Main Floor	Technical Sessions
		06-03: Advanced Hybrid Electronics Processing & Reliability - I	02-04: Single Phase Liquid Cooling - II (Technical)	03-05: Electronics Packaging - Solder II	Flexible Electronics	Panel
12:45 PM	2:00 PM	Room: Hermosa/Huntington/Manhattan, Main Floor				Lunch Presentation
		Lunch InterPACK'25 Allan Kraus Award				
2:00 PM	3:30 PM	Room: The Palm, Main Floor		Room: International Center, Main Floor		Workshops
		The DOE Vehicle Technologies Office (VTO) Next Generation Electric Drive (NEXTDRIVE) Program		PROBABILISTIC DESIGN for RELIABILITY (PDfR) CONCEPT, and the Roles of Failure Oriented Accelerated Testing (FOAT) and Predictive Analytical ("Mathematical") Modeling		Tutorials
3:30 PM	3:45 PM	Room: Grand Foyer, Main Floor				Break
		Coffee Break				
3:45 PM	5:15 PM	Room: Lassen, 2nd Floor	Room: Tahoe/Redwood, 2nd Floor	Room: Yosemite, 2nd Floor	Room: The Palm, Main Floor	Technical Sessions
		02-05: Two Phase Cooling - II (Technical)	04-02: Power/RF Electronics and Photonics - Wide Bandgap Semiconductors and Photonics	05-01: Multiscale Thermal Transport and Energy Storage - I	Energy Efficiency and Sustainable Technologies	Tutorials
5:15 PM	6:30 PM	Room: The Palm, Main Floor		Room: Laguna, Main Floor		Tutorials
		K16 Mentoring Program		Machine Learning & Liquid Cooling		Workshops
6:30 PM	7:00 PM	Room: International Center				ASME Meetings
		InterPACK Meeting(Closed)				
7:00 PM	7:30 PM	Room: International Center				ASME Meetings
		InterPACK (Open)				
7:30 PM	8:00 PM	Room: International Center				ASME Meetings
		K-16 Committee Meeting (Open)				

Time		Day 4: Thursday - October 30, 2025				
From	To	Room/Event				Type
8:00 AM	8:45 AM	Room: California Ballroom, Main Floor				Pleanary Session
		Unlocking Human Potential through Haptic Sharing By Prof. Yoshihiro Tanaka (Nagoya Institute of Technology)				
8:45 AM	9:30 AM	HAMR Interface Reliability Challenges By Dr. Qing Dai (Western Digital)				
9:30 AM	11:00 AM	Room: Lassen, 2nd Floor	Room: Sequoia, 2nd Floor	Room: Tahoe/Redwood	Room: Laguna, Main Floor	Technical Sessions
		06-04: Advanced Hybrid Electronics Processing & Reliability - II	01-02: Heterogeneous Integration- II	11-02:Advanced Simulation in Science and Engineering - II	Special Session: NREL Activities and Capabilities in Electronics Packaging Across Multiple Applications	Workshops
11:00 AM	11:15 AM	Room: Grand Foyer				Break
		Coffee Break				
11:15 AM	12:45 PM	Room: Lassen, 2nd Floor	Room: Sequoia, 2nd Floor	Room: Tahoe/Redwood, 2nd Floor	Room: The Palm	Technical Sessions
		10-01:Mechatronics, Tribology, and Control of Information Storage Systems and Robotics	05-02: Multiscale Thermal Transport and Energy Storage - II	02-06: Two Phase Cooling - III	Mechanics and Reliability	Panel

12:45 PM	2:00 PM	Room: Hermosa/Huntington/Manhattan, Main Floor				Lunch Presentation
		Lunch InterPACK'25 Awards (Nasser Grayeli Poster, EPPD, JEP)				
2:00 PM	3:30 PM	Room: Laguna, Main Floor		Room: Newport, Main Floor		Panel
		Data Center Power and Cooling Technologies		Additive and Alternative Manufacturing for Electronics		Tutorials
3:30 PM	3:45 PM	Room: Grand Foyer				Break
		Coffee Break				
3:45 PM	5:15 PM	Room: Lassen, 2nd Floor	Room: Tahoe/Redwood, 2nd Floor	Room: Yosemite, 2nd Floor	Room: Laguna, 2nd Floor	Technical Sessions
		03-06: Electronics Packaging - Substrates, Underfill and TIMs	06-05: Stretchable & Wearable Electronics	09-02: Micro/Nano Mechatronics, Microelectronics, Microelectrochemical Systems, and their Applications of Internet of Things - II	Session 05-04: Multiscale Thermal Transport and Energy Storage - IV	